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| FORM PTO-1449 (REV.7-80) | U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE | ATTY. DOCKET NO. 30022/US/3 | APPLICATION NO. 10/675,965 Not Yet Assigned |
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| **INFORMATION DISCLOSURE STATEMENT** *(Use several sheets if necessary)* | | APPLICANT(S) Sion C. Quinlan and Tim J. Bales | |
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| ↓ | BP | Microprocessor and Microcomputer Standards Committee of the IEEE Computer Society, "P1394a Draft Standard for a High Performance Serial Bus (Supplement)," The Institute of Electrical and Electronics Engineers, Inc., June 30, 1999, pp.1-27 |
| ↓ | BQ | Lucent Technologies, Inc., "IEEE 1394 Isolation," Application Note, November 1998, obtained at website "http://www.agere.com/1394/docs/AP98074-01.pdf," pp. 1-16 |

| EXAMINER | DATE CONSIDERED |
|---|---|
| Jinghua Jin | 4/15/2006 |

* EXAMINER: Initial if reference considered, whether or not criteria is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant(s).

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| | | FILING DATE September 30, 2003 | GROUP ART UNIT 2811 J. Im |



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| *EXAMINER INITIAL | | DOCUMENT NUMBER | DATE | NAME | CLASS | SUBCLASS | FILING DATE IF APPROPRIATE |
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| | AD | | | | | | |
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## FOREIGN PATENT DOCUMENTS

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### U.S. PATENT DOCUMENTS

| *EXAMINER INITIAL | | DOCUMENT NUMBER | DATE | NAME | CLASS | SUBCLASS | FILING DATE IF APPROPRIATE |
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